



PTP81708T06

SMD Type Phototransistor

Features

- Small double-end package
- High photo sensitivity
- High reliability
- Spectral range of sensitivity: 400-1100nm
- Fast Response time
- RoHS compliance

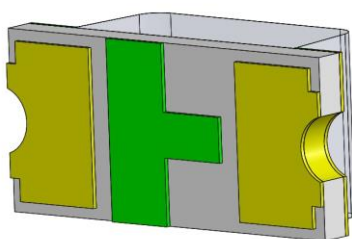
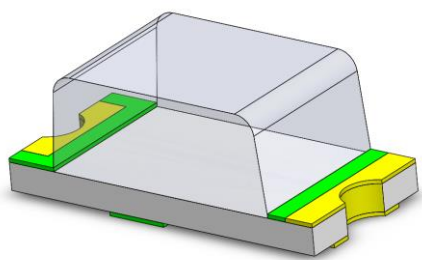
Applications

- Infrared sensor
- Infrared Touch Panel Solutions

Description

The PTP81708T06 is silicon NPN Phototransistor
The device has wide spectral sensitivity range from 400 to 1100nm.

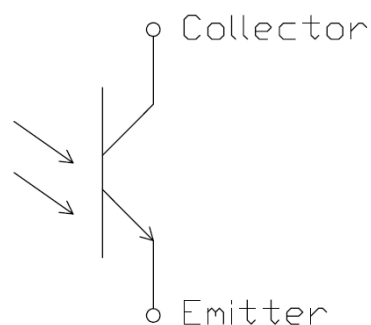
Package Outline



Emitter

Collector

Schematic



**Absolute Maximum Rating at 25°C**

Symbol	Parameters	Ratings	Units	Notes
I _C	Collector Current	20	mA	
B _V CEO	Collector-Emitter Voltage	35	V	1
B _V ECO	Emitter-Collector Voltage	5	V	2
T _{opr}	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	3
P _{to}	Total Power Dissipation	150	mW	

Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
λ	Spectral Bandwidth	-	400	-	1100	nm	
λ _P	Peak Sensitivity	-	-	820	-	nm	
θ _{1/2}	View Angle	V _{CE} =5V	-	±65	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _{CEO}	Dark Current	E _e =0mW /cm ² V _{CE} =20V	-	-	100	nA	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	E _e =1mW /cm ² I _C =0.3mA	-	-	0.4	V	
I _C	Collector Light Current	E _e =1mW /cm ² λ _P =940nm, V _{CE} =5V	0.3	0.8	-	mA	
C _T	Terminal Capacitance	E _e =0mW /cm ² f=1MHz, V _{CE} =5V	-	2.45	-	pF	

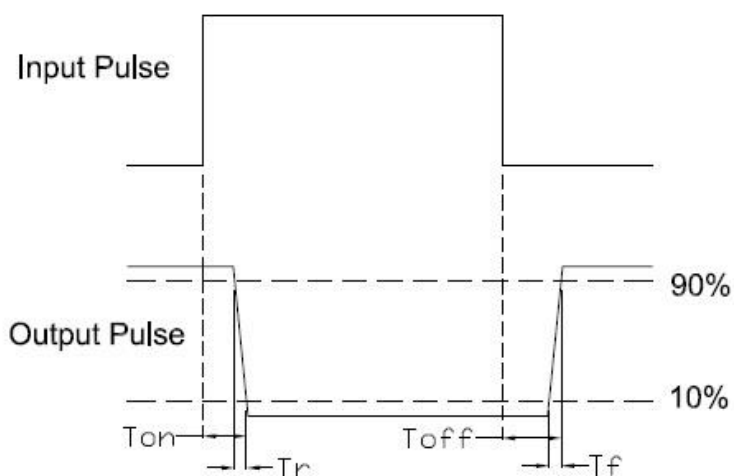
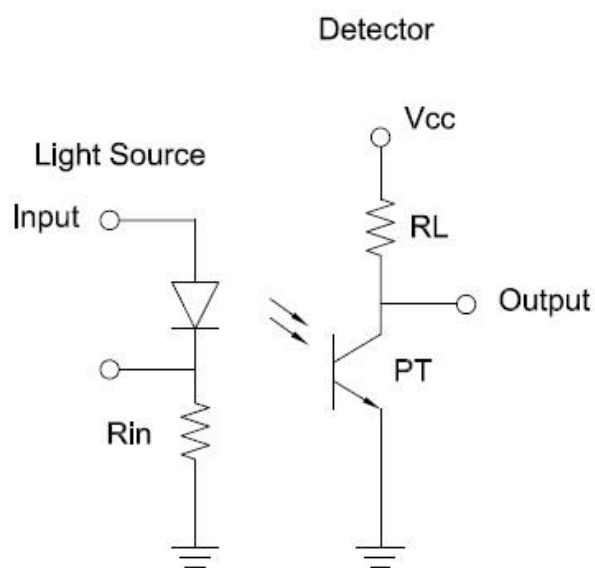


Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
t_r	Rise Time	$V_{ce} = 5V, R_L = 100\Omega$ $I_C = 1.0mA$	-	6	-	μs	4
t_f	Fall Time		-	7	-		
t_{on}	Turn on Delay Time		-	11	-		
t_{off}	Turn off Delay Time		-	7.9	-		

Notes:

- 1 : Test conditions : $I_C = 100\mu A, E_e = 0mW/cm^2$.
- 2 : Test conditions : $I_E = 100\mu A, E_e = 0mW/cm^2$.
- 3 : Soldering time ≤ 5 seconds.
- 4 : Test circuit:



Switching Time



Typical Characteristic Curves

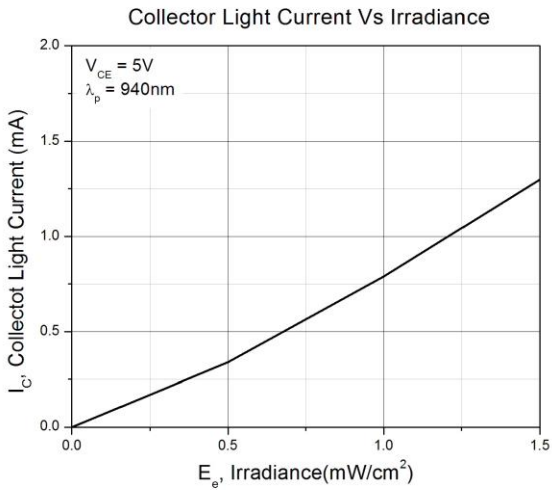


Figure 1

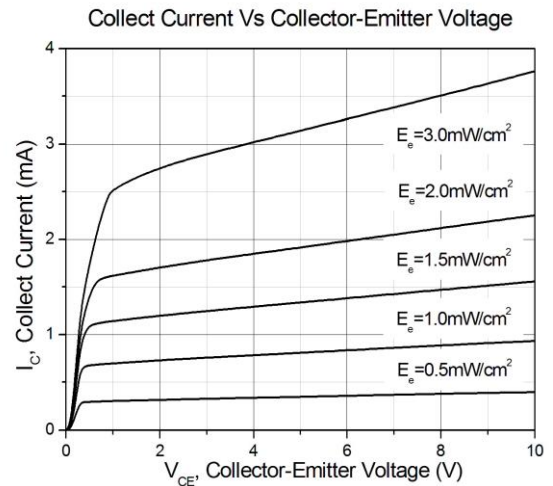


Figure 2

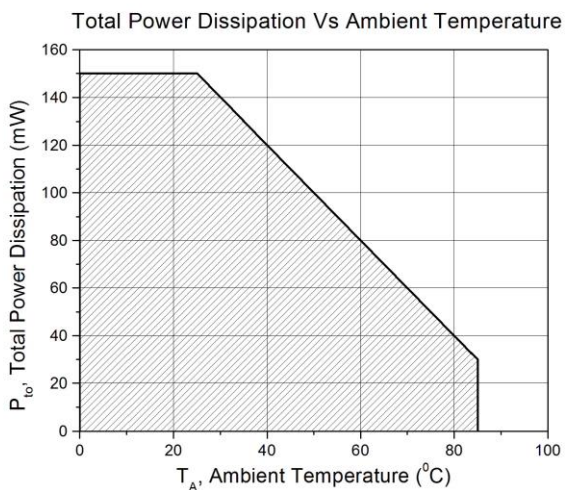


Figure 3

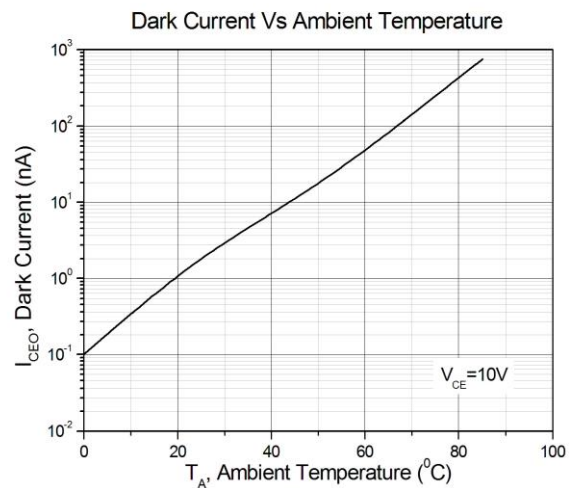


Figure 4

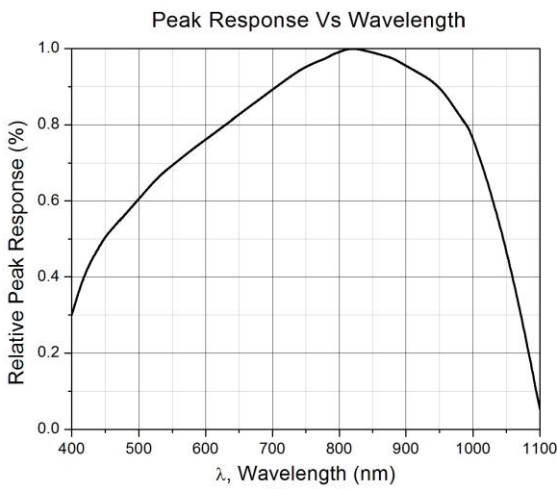


Figure 5

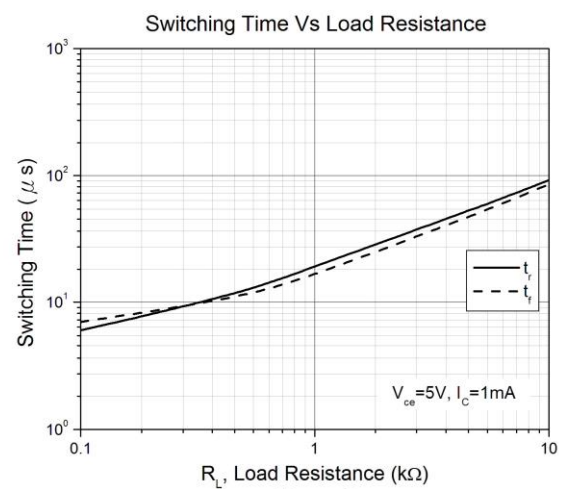
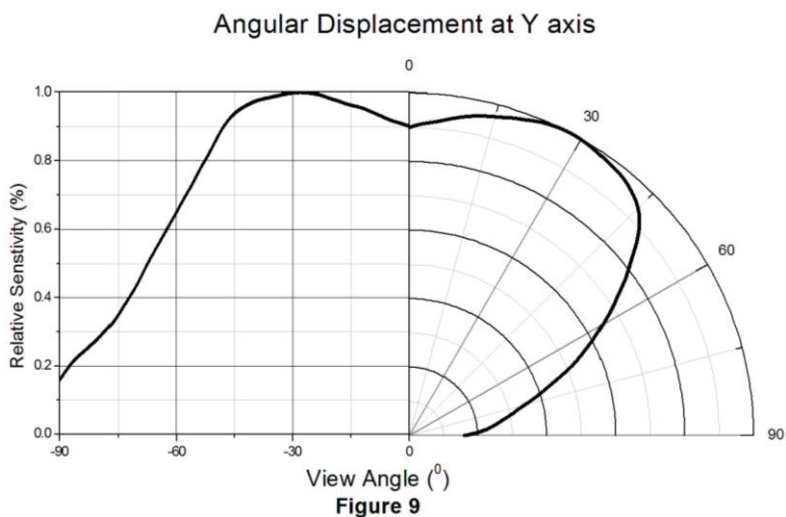
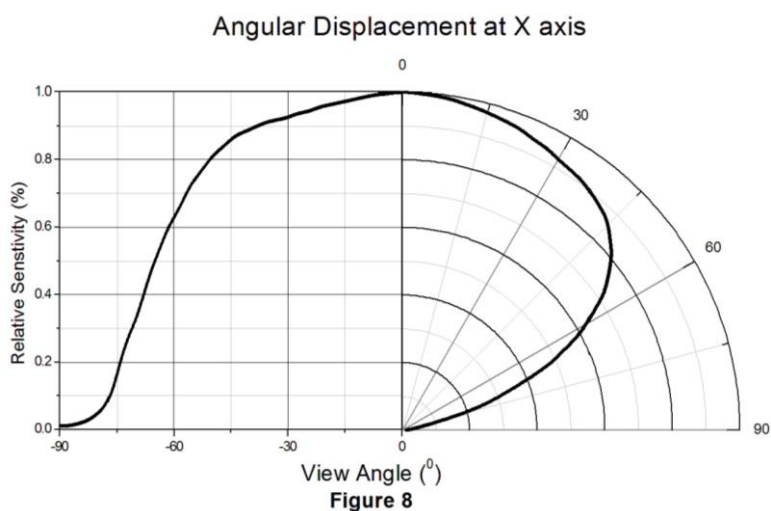
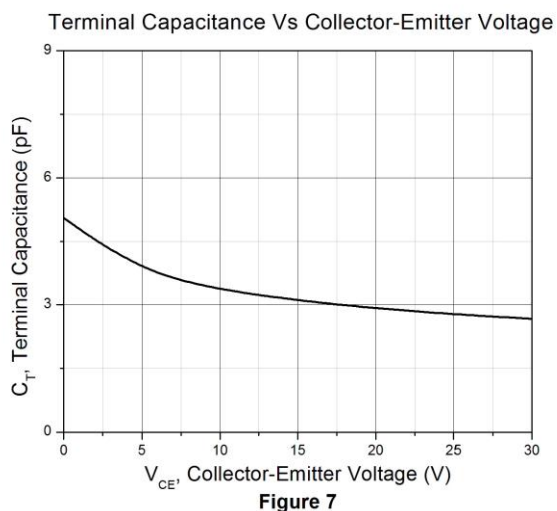


Figure 6

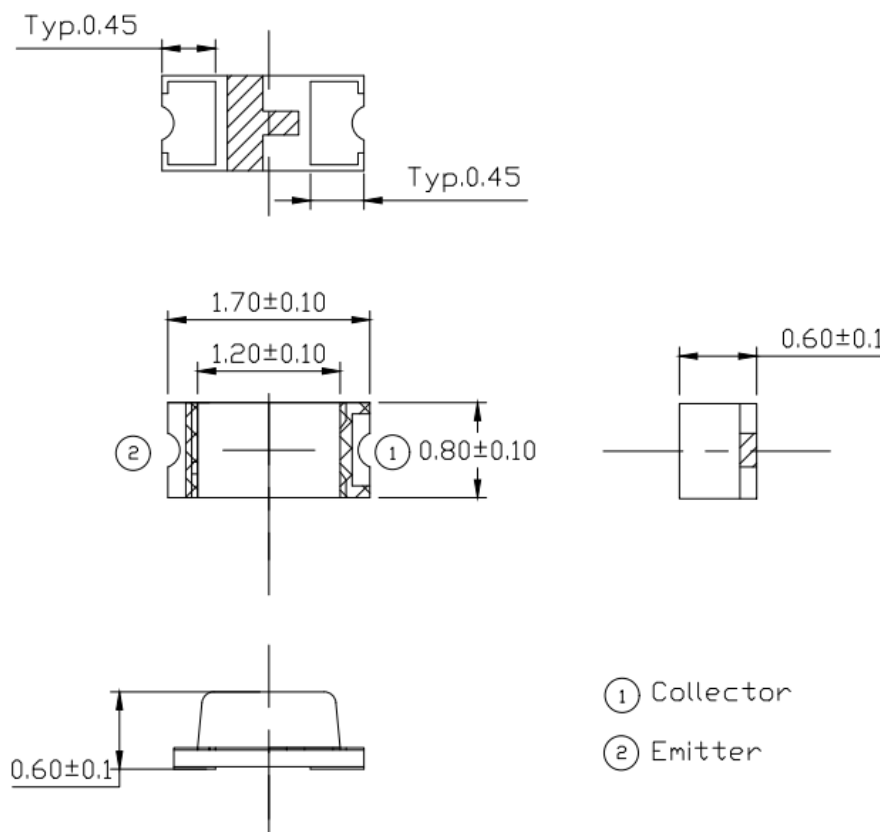


Typical Characteristic Curves

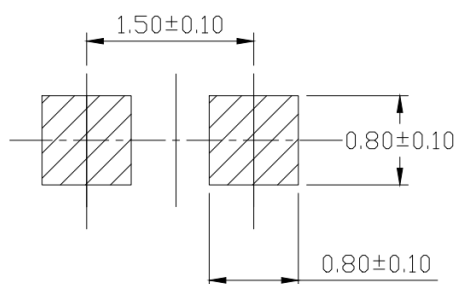




Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*

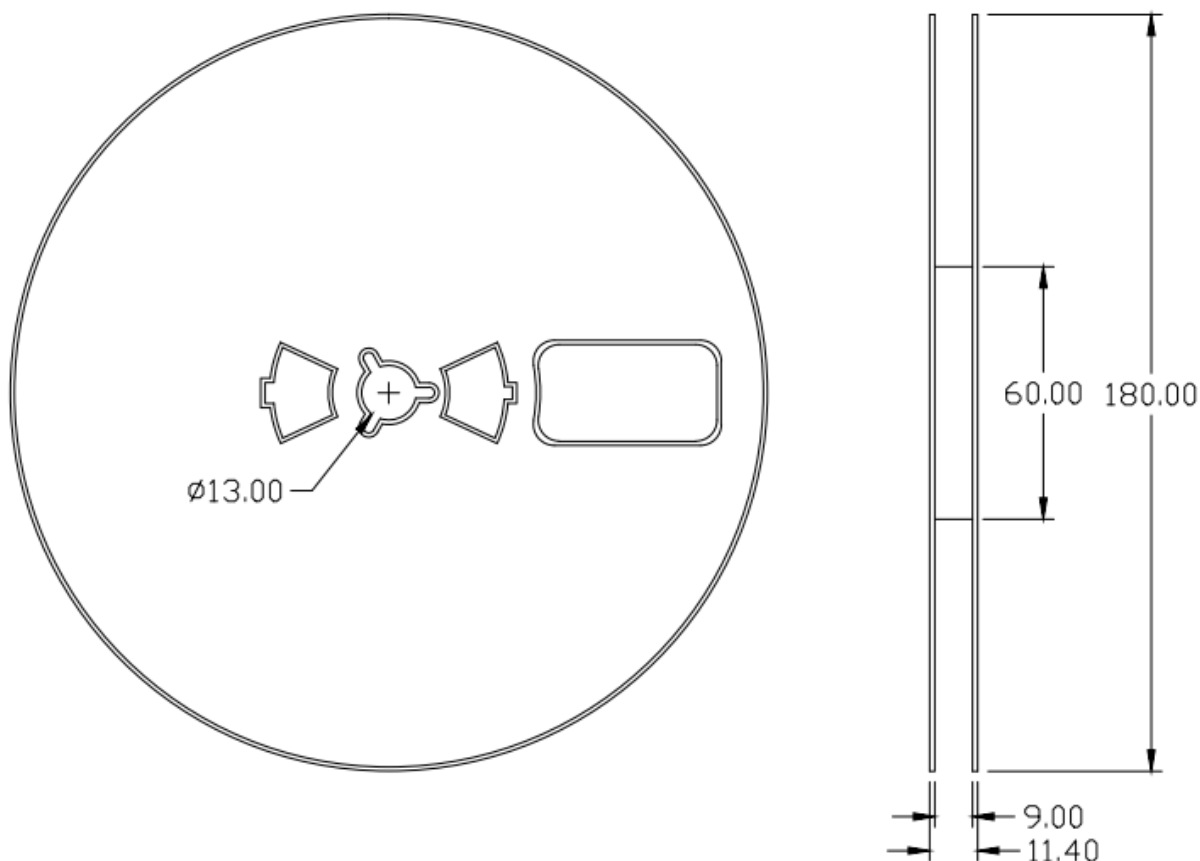


Ordering Information

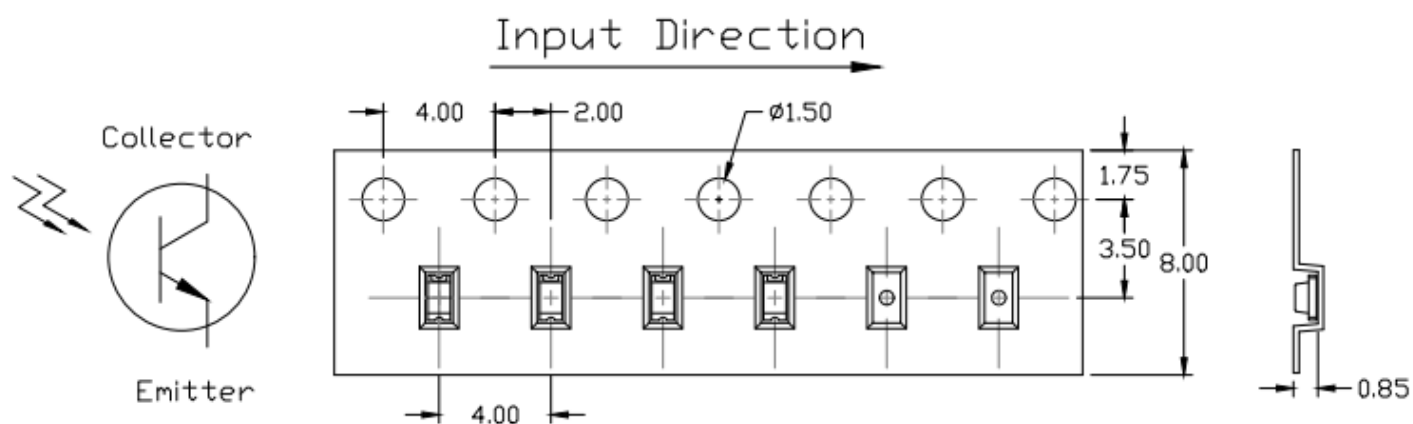
Part Number	Description	Quantity
PTP81708T06	Tape & Reel	4000 Pcs



Reel Dimension *All dimensions are in mm, unless otherwise stated*

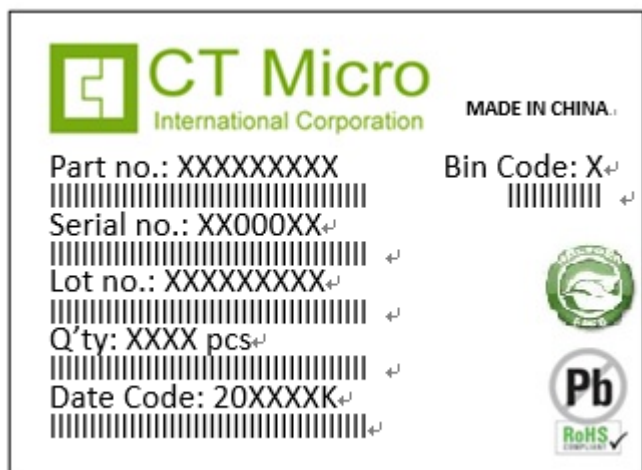


Tape Dimension *All dimensions are in mm, unless otherwise stated*





Label Form Specification



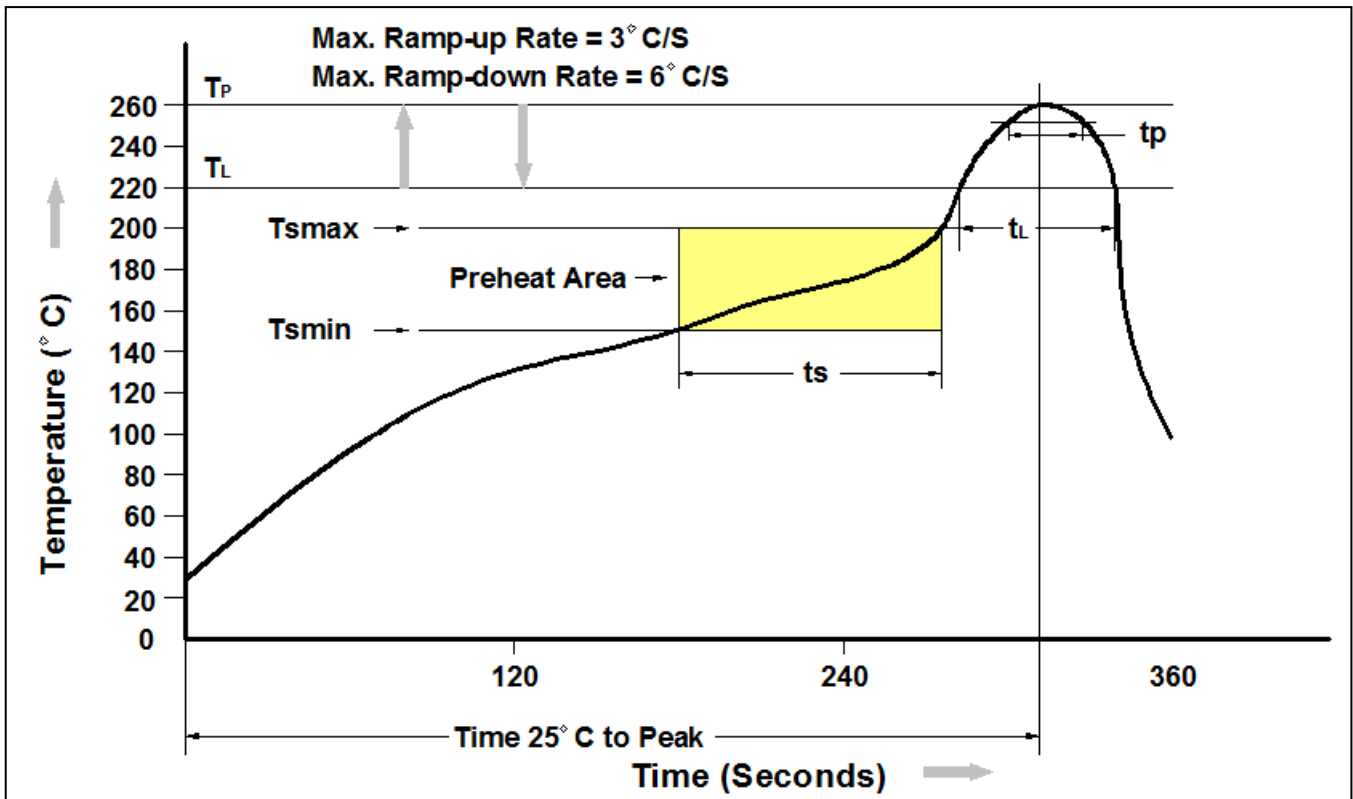
Part no: CTM Production Number
 Serial no: Production Number
 Lot no: Lot number
 Q'ty: Packing Quantity
 Date Code: Manufacture Date
 Bin Code: Ic Ranks
 MADE IN CHINA: Production Place

Storage Condition

1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{sm})	150°C
Temperature Max. (T _{sm})	200°C
Time (t _s) from (T _{sm} to T _{sm})	60-120 seconds
Ramp-up Rate (t _L to t _p)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _p) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _p to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*